L MULTIPLEX TERMINALS MMX-1

TRANSMITTING SUBMASTER GROUP BANK GAIN TESTS

PURPOSE OF TESTS

- (a) To ensure that the output level is correct.
- (b) To ensure that the passband is correct.

REASON FOR REISSUE

To include reference to solid-state amplifiers in modified MMX-1 transmitting submaster group bank panels. Arrows are used to indicate significant changes. **Equipment Test Lists are not affected.**

SYNOPSIS (Fig. 2)

The transmitting submaster group bank circuit provides a means for translating the output frequencies from the supergroup banks into the proper frequency band, and at the proper power for transmission to a transmitting MMX-1 mastergroup bank.

Each submaster bank contains two transmission paths, submaster group 1 and submaster group 2. The output frequencies from the supergroup banks are received at the submaster group hybrids, amplified, and transmitted to the mastergroup. Submaster group 1 frequencies are transmitted to the mastergroup with no additional frequency translation. Submaster group 2 uses two stages of modulation to shift the output frequencies from the supergroup banks to the proper frequency band for transmission to the mastergroup.

APPARATUS

Transmission Test Equipment. Refer to Section 356-010-500 and select, from available equipment, sending and receiving units having the following capabilities:

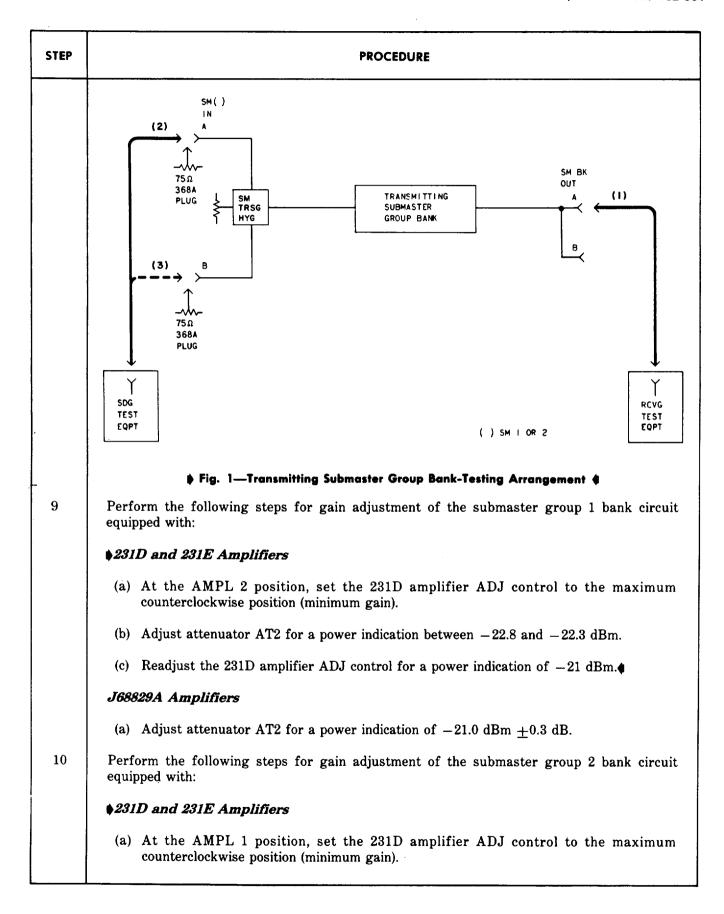
Sending test equipment capable of delivering, into 75-ohm circuits, signals between 320 kHz and 2040 kHz at -43.4 dBm

Receiving test equipment capable of detecting, from 75-ohm circuits, signals between 320 kHz and 3080 kHz at powers between -15 dBm and -25 dBm.

P2BJ Cords

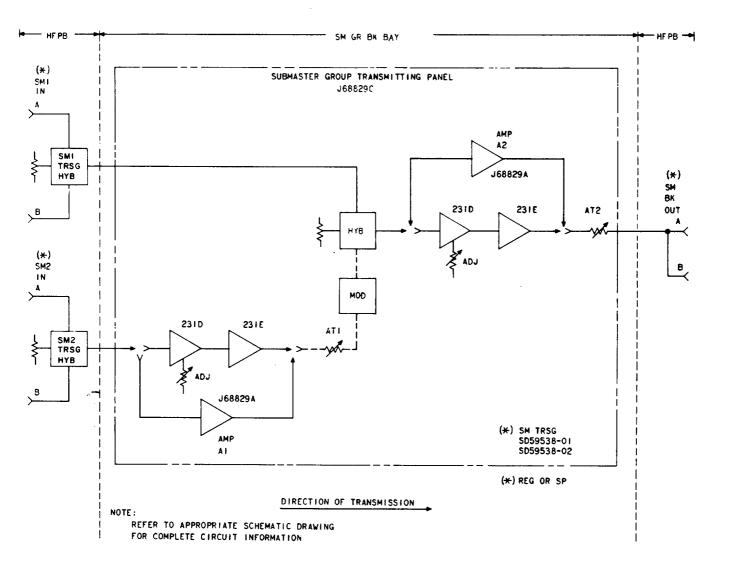
368A Plugs

STEP	PROCEDURE												
	GAIN TESTS												
	Note: Refer to Fig. 2 to determine the location of jacks and controls used in this test.												
	Caution: Gain adjustments of the submaster group 1 bank circuit change the overall gain of the submaster group 2 bank circuit. Therefore, the gain of the submaster group 1 circuit must be checked and if necessary, adjusted prior to testing the submaster group 2 circuit. Check that the equipment to be tested is out-of-service.												
1													
2	Prepare the STE (sending test equipment) to produce a signal at the send frequency and power in Table A for the submaster group bank circuit to be tested.												
			♦ TABLE A ♦										
						GAIN TEST	rs						
		SM	SEND			RECEIVE							
		GROUP BANK	JACK	FREQ (KHZ)	POWER (DBM)	JACK	FREQ (KHZ)	REQUIREMENT	GAIN ADJUSTMENT				
	_	1	SM 1 IN A SM 1 IN B	1500	-43.4	SM BK OUT A	1500	-21.0 dBm ±0.3 dB	Step 9				
		2	SM 2 IN A SM 2 IN B	1500	-43.4	SM BK OUT A	2540	-21.0 dBm ±0.3 dB	Step 10				
3		receive	e the RTE (rece frequency at — et the RTE to the	·21 dBm	•			nm terminated measure	ment of the				
5		Connec	et the STE to the	e SM()	IN A jacl	k [patch (2)	, Fig.	1].					
	Note: Parentheses () denote SM1 or SM2.												
6		Insert a 75-ohm 368A plug in the SM() IN B jack.											
7		Measure and record the power of the signal at the SM BK OUT A jack.											
	Requirement: -21.0 dBm ±0.3 dB.												
8	If the requirement of Step 7 is met, proceed to Step 12. If it is not met, remove th panel cover from the submaster group bank circuit under test and perform trouble clearing procedures in Step 9 or 10 as applicable.												



STEP	PROCEDURE						
	(b) Adjust attenuator AT1 for a power indication between -22.8 and -22.3 dBm.						
	Caution: Do not change the setting of attenuator AT2.						
	(c) Readjust the 231D amplifier ADJ control for a power indication of −21 dBm.						
	29A Amplifiers						
	(a) Adjust attenuator AT1 for a power indication of $-21.0~\mathrm{dBm}~\pm0.3~\mathrm{dB}$.						
	Caution: Do not change the setting of attenuator AT2.						
11	If the requirement of Step 7 cannot be met, locate and correct the trouble in the submaster group bank circuit under test. Repeat Steps 7 through 10 as required.						
	Note: J68829A flat-gain amplifiers should be replaced only after tube replacements have been made.						
12	Disconnect the STE from the SM() IN A jack [patch (2), Fig. 1].						
13	Remove the 75-ohm 368A plug from the SM() IN B jack.						
14	Insert a 75-ohm 368A plug in the SM() IN A jack.						
15	Connect the STE to the SM() IN B jack [patch (3), Fig. 1].						
16	Measure the power of the signal at the SM BK OUT jack.						
	Requirement: -21.0 dBm ±0.3 dB.						
17	Disconnect the STE from the SM() IN B jack [patch (3), Fig. 1].						
18	Remove the 75-ohm 368A plug from the SM() IN A jack.						
19	Insert a 75-ohm 368A plug in the SM() IN B jack.						
20	If the passband tests are to be made, proceed to Step 21; otherwise, proceed to Step 25.						
	PASSBAND TESTS						
21	Prepare the STE to produce a signal at the send frequency and power (Table B) for the submaster group bank circuit under test.						
22	Prepare the RTE for a 75-ohm terminated measurement of the receive frequency at -21 dBm.						

					PROCEDURE										
	♦ TABLE B ♦														
PASSBAND TESTS															
SM	SEND			RECEIVE											
GROUP BANK	JACK	FREQ (KHZ)	POWER (DBM)	JACK	FREQ (KHZ)	REQUIREMENT									
1	SM 1 IN A	320	-43.4	SM BK OUT A	320	Within +0.1 dB to +1.1 dB of the power recorded in Step 7.									
1	SM I IN A	2040			2040	Within -0.8 dB to +0.2 dB of the power recorded in Step 7.									
2	SM 2 IN A	1064	-43.4	SM BK OUT A	2104	Within +0.0 dB to +1.0 dB of the power recorded in Step 7.									
		2040			3080	Within -1.2 dB to -0.2 dB of the power recorded in Step 7.									
Measure and record the power at the SM BK OUT A jack at each of the passband frequencies (Table B) for the submaster group bank under test.															
Require	ement: See Tal	ole B.													
If the requirements of Step 23 are met, proceed to Step 25. If they are not met, locate and correct the trouble in the submaster group bank circuit under test (<i>Note</i> , Step 11). Repeat Steps 2 through 23, as required, to verify that the trouble has been cleared.															
Replace	the panel cover	if remo	ved in Ster	o 8.											
Remove all patches from the submaster group bank circuit under test.															
Restore the equipment to normal service.															
	Measure (Table E Require If the r and cor Repeat t Replace	1 SM 1 IN A 2 SM 2 IN A Measure and record the (Table B) for the submate the requirement: See Table 1 Table 1 Table 1 Table 2 Table 2 Table 2 Table 3 Table	SM GROUP BANK JACK FREQ (KHZ) 320 1 SM 1 IN A 2040 2040 Measure and record the power a (Table B) for the submaster gro Requirement: See Table B. If the requirements of Step 23 and correct the trouble in the Repeat Steps 2 through 23, as relations are removed. Remove all patches from the submove and patches from the submove all patches from the submove and	1 SM 1 IN A 2040 1 SM 2 IN A 2040 Measure and record the power at the SM E (Table B) for the submaster group bank us Requirement: See Table B. If the requirements of Step 23 are met, and correct the trouble in the submaster Repeat Steps 2 through 23, as required, to Replace the panel cover if removed in Step Remove all patches from the submaster group and the s	1 SM 1 IN A 2040 SM 2 IN A Measure and record the power at the SM BK OUT A ja (Table B) for the submaster group bank under test. Requirement: See Table B. If the requirements of Step 23 are met, proceed to and correct the trouble in the submaster group bank Repeat Steps 2 through 23, as required, to verify that Replace the panel cover if removed in Step 8. Remove all patches from the submaster group bank circles.	SM GROUP BANK JACK FREQ (KHZ) POWER (KHZ) JACK FREQ (KHZ) 320 1 SM 1 IN A 2040 2040 2040 SM BK OUT A 2040 2040 Measure and record the power at the SM BK OUT A jack at ea (Table B) for the submaster group bank under test. Requirement: See Table B. If the requirements of Step 23 are met, proceed to Step 25 and correct the trouble in the submaster group bank circuit Repeat Steps 2 through 23, as required, to verify that the trous Replace the panel cover if removed in Step 8. Remove all patches from the submaster group bank circuit under the submaster									



♦ Fig. 2—Submaster Group Bank Transmitting Circuit ♠